新一代应用于VCP的电镀锡技术
New Tin Plating Technology for VCP Application

SOLDERON™ VP-200 Tin Electroplating Bath

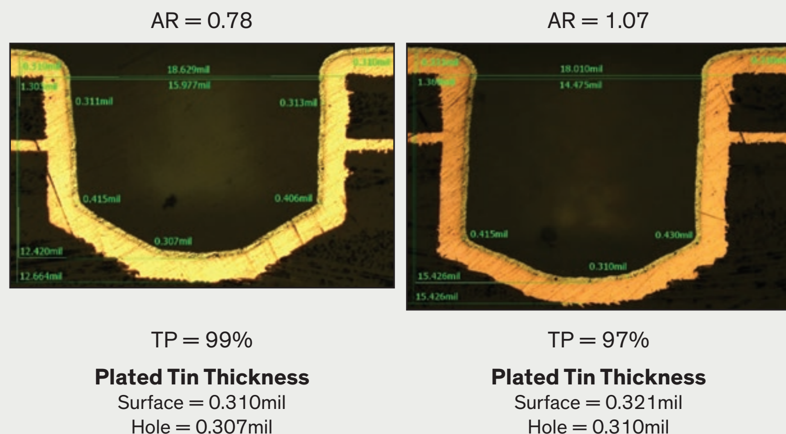
Dow Electronical Material offers SOLDERON™ VP-200 as new Tin plating product with characteristic of high performance, environmental friendliness, and low foaming. This product is designed to VCP application.

陶氏化学电子材料提供 SOLDERON VP-200具有高效能,环保和低泡沫特性运用于VCP的新世代电镀锡技术。

Advantage of New Tin Process 新电镀锡制程的特性

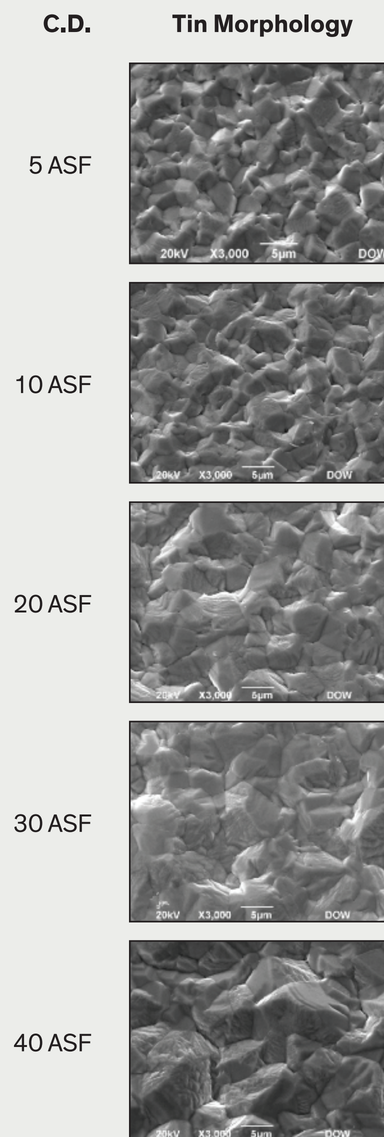
- Eco-friendly formulation
  环保配方
  - NPE/APE free
    不使用壬基苯酚类之界面活性剂
- Higher alkaline etching resistant
  高抗碱能力
  - Uniform, large and well-polygonized deposit at all range of current density
    在不同电流密度下为紧密的多边形晶格的镀锡层结构
- Low foaming
  低泡沫特性
  - Suitable to VCP line
    适用于VCP线
- Robust to organic contamination from dry film leaching
  对乾膜析出的有机污染具有高容忍度

TP performance at different Aspect Ratio of M/C drilling hole
在不同纵横比的机钻盲孔之深镀能力表现



AR = 0.78	AR = 1.07
TP = 99%	TP = 97%
Plated Tin Thickness	**Plated Tin Thickness**
Surface = 0.310mil	Surface = 0.321mil
Hole = 0.307mil	Hole = 0.310mil

Plating appearance and morphology
镀层外观和表面形貌



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